



MULTILAYER CERAMIC CAPACITORS

3-Terminal Capacitor Series (FT)

Feed Through Type 0805 Size (10V to 50V) X7R Dielectric

PASSIVE S

Halogen Free & RoHS Compliance

Preliminary spec

*Contents in this sheet are subject to change without prior notice.



1. DESCRIPTION

This product specification is applied to 3-terminal Capacitor for FT Series used for General Electronic equipment. WTC capacitor Feed Through type are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

2. FEATURES

- a. High density mounting due to mounting space saving.
- b. Mounting cost saving.
- c. Increased throughput.

3. APPLICATIONS

- a. For use as a bypass for digital and analog signal line noise
- b. Computer motherboards and peripherals.
- c. The other common electronic circuits.

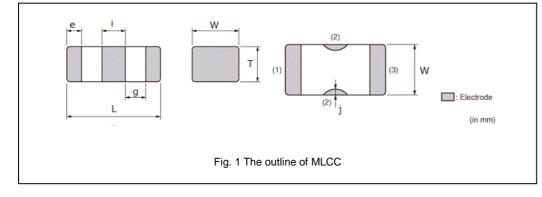
4. HOW TO ORDER

<u>FT</u>	<u>21</u>	<u>B</u>	<u>105</u>	<u>M</u>	<u>160</u>	<u>C</u>	Ī
Series	<u>Size</u>	Dielectric	Capacitance	Tolerance	Rated voltage	Termination	Packaging
FT= Feed Through Capacitor	21 =0805 (2012)	B=X7R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF $105=10x10^5$ =1000nF=== =1µF	一日	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC	C =Cu/Ni/Sn	T=7" reeled





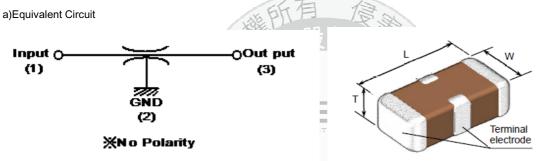
5. EXTERNAL DIMENSIONS



Brand	L (mm)	W (mm)	T (mm)/Sym	ibol	e (mm)	g (mm)	i (mm)	j(mm)
0805	2.00±0.20	1.25±0.10	0.85±0.10	т	0.30±0.20	0.40±0.20	0.60±0.20	0.25±0.20

Reflow soldering process only.

6. Rated value



		01					
WTC PART NO.	Nominal Capacitance	Capacitance Tolerance	DC Rated Voltage	Rated Current (mA)	DC Resistance	Insulation Resistance	Operating Temp. Range
FT21B103M500	10 nF	±20%	DC50 V_0	2A(DC)	0.03Ωmax	1000MΩmin	-55 to 125°C
FT21B223M500	22 nF	±20%	DC50 V	2A(DC)	0.03Ωmax	1000MΩmin	-55 to 125°C
FT21B473M500	47 nF	±20%	DC50 V	2A(DC)	0.03Ωmax	1000MΩmin	-55 to 125°C
FT21B104M250	0.1 uF	±20%	DC25 V	2A(DC)	0.03Ωmax	1000MΩmin	-55 to 125°C
FT21B224M160	0.22 uF	±20%	DC16 V	2A(DC)	0.03Ωmax	1000MΩmin	-55 to 125°C
FT21B474M160	0.47 uF	±20%	DC16 V	2A(DC)	0.03Ωmax	1000MΩmin	-55 to 125°C
FT21B105M160	1 uF	±20%	DC16 V	4A(DC)	0.02Ωmax	500MΩmax	-55 to 125°C

* Measured at the condition of 30~70% related humidity.

X7R/X6S/X5R/X7S: Please refer to page 5 "Reliability test conditions and requirements" for detail.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour and then leave in ambient condition for 48±2 hours before measurement.

7. GENERAL ELECTRICAL DATA

No	Item	Specification	Test Method
1	Capacitor(Cap.)	Meet item 6.	Frequency : 1.0±0.1kHz
			Voltage : 1±0.2V(rms)
2	Insulation Resistance(I.R.)	Meet item 6	Voltage : Rated Voltage
	· · · ·		Time : 2 minutes max.
3	DC Resistance	As for Direct Current spec of each product, please	Measured with 100mA max.
		refer to item 6 Measuring current shall be 100mA max Rdc I	
4	Withstanding Voltage	Products shall not be damaged.	Test Voltage : Rated Voltage x 300% Time : 1 to 5 s
			Charge Current : 50 mA max.
5	Operating Temperature	Shown in item 6.	Includes self-heating
6	Storage Temperature	5 to 40°C at 20 to 70%RH	

* Measured at 30~70% related humidity.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 25℃ ambient temperature.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 48±2 hours before measurement.

8. CAPACITANCE RANGE

			X		
	SIZE Inch (mm)			[21 (2012)	
	DIELECTRIC		X	7R	
RA	ATED VOLTAGE (VDC)	10	16	25	50
	10nF (103)	Т	T		Т
	22nF (223)	Т	Т	J	Т
	47nF (473)	Т	Т	T.	67h
	0.10µF (104)	Т	Т	Ť.	Tra
	0.22µF (224)	Т	Т		SCHNOIT
	0.47µF (474)	Т	Т		
	1µF (105)	Т	Т		

1. The letter in cell is expressed the symbol of product thickness.

9. PACKAGING DIMENSION AND QUANTITY

SIZE Inch (mm)	Thickness/Symbol (mm)		Packing		Packing Unit
0805	0.85±0.10	т	180mm Reel PAPER	4000 pcs./Reel	

Unit: pieces

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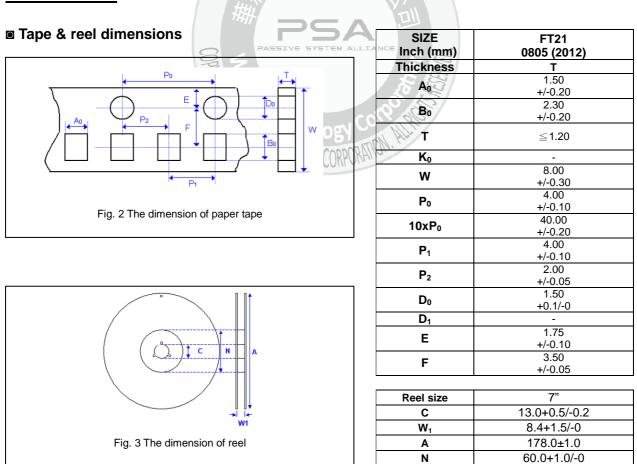
10. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem		Test Condition		Requirements		
1.	Appearance	Visual Inspecti	on and measured with S	lide Calipers.	* No remarkable defect. * Dimensions to conform to individual specification sheet.		
	and						
	Dimensions						
2.	Capacitance	Frequency : 1.0	0±0.1kHz		* Shall not exceed the limits g	iven in the detailed spec.	
		Voltage : 1±0.2	?V(rms)				
3.	Solder ability	* Solder temper	ature: 240±3℃		90% min. coverage of all met	alized area.	
		* Dipping time: 2	2±0.5 sec.				
4.	Resistance to		ature: 270±5℃		Meet table 1.		
	Soldering Heat				Table 1		
			0 to 150℃ for 1 minute be	efore imme rse the	Appearance	No damaged	
		capacitor in a e			Cap. Change	Within±7.5%	
			easurement (Class II only		I.R.	Meet the initial rated value.	
			then set for 48±4 hrs at ro		DC Resistance	0.05Ω max	
			surement to be made after for 48±4 hrs at room temp		* 25% max. leaching on each	edge.	
5.	Bending Test		red on the glass-epoxy su	2	Meet table2.		
		(100×40×1.0mn	ı).				
		Table 2 Deflecti	on : 2 mm	古阳份;	Table2		
		Keeping Time :	30 s Pressu	ire jig	Appearance	No damaged	
			R5 F		Cap. Change	Within±7.5%	
		Ľ			DC Resistance	0.05Ω max	
		(45 45 Product				
6.	Adhesive	* Pressurizing for	orce : S		* No remarkable damage or re	emoval of the terminations.	
	Strength of	5N (≤0603) and	Z				
	Termination	* Test time: 30±	1 sec.				
7.	Vibration	* Vibration frequ	iency: 10~55 Hz/min.		Meet Table 3.		
	Resistance	* Total amplitude	e: 1.5mm	Chhology	Table3		
		* Test time: 6 hr	s. (Two hrs each in three r	mutually	Appearance	No damaged	
		perpendicular d	irections.)	WOLDGY (ORPOR	Capacitance	Meet the initial rated value	
		*Before initial m	easurement (Class II only): To apply de-aging	DC Resistance	0.05Ω max	
			then set for 48±4 hrs at ro				
			nent to be made after de-a	aging at 150°C for			
		1hr then set for	48±4 hrs at room temp.				
8.	Temperature	Conduct the 10	cycles according to the te	mperatures and time	Meet table 4.		
	Cycling		_		Table 4		
		Step	Temp. (°C)	Time (min.)	Appearance	No damaged	
			pperating temp. +0/-3	30±3	Cap. Change	Within±7.5%	
			temp. operating temp. +3/-0	2~3 30±3	I.R.	Meet the initial rated value.	
			temp.	2~3	DC Resistance	0.05Ω max	
		·ł					
		*Before initial m	easurement (Class II only): To apply de-aging			
		at 150℃ for 1hr	then set for 48±4 hrs at ro	oom temp.			
		* Cap. / I.R. Me	asurement to be made afte	er de-aging at 150℃			
		for 1hr then set	for 48±4 hrs at room temp).			
		Total of 10 cycle	6		•		



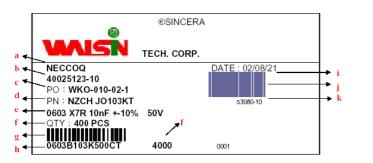
No.	ltem	Test Condition	Requ	irements	
9.	Humidity	* Test temp.: 40±2℃	Then measured after exposure in the room condition for 48±4 hours		
	(Damp Heat)	* Humidity: 90~95% RH	If it's doubt, the measuring has	to be done after 1 hours curing	
	Steady State	* Test time: 500+24/-0hrs.	at 150+0 / -10℃ and 48±4 hour	s storage.	
		*Before initial measurement (Class II only): To apply de-aging	Meet Table5.		
		at 150°C for 1hr then set for 48±4 hrs at room temp .	Table5		
		* Cap. / I.R. Measurement to be made after de-aging at $150 \ensuremath{\mathbb{C}}$	Appearance	No damaged	
		for 1hr then set for 48±4 hrs at room temp.	Cap. Change	Within±12.5%	
			I.R.	50Ω·F min	
			DC Resistance	0.05Ω max	
10.	High	Temperature : Maximum Operating Temperature ± 2 °C			
	Temperature	Test Voltage : Rated Voltage x 200%	Then measured after exposure	e in the room condition for 48±4	
	Load	Charge Current : 50 mA max.	hours.		
	(Endurance)	Time : 1000+48 / -0 hours	If it's doubt, the measuring has to be done after 1 hours curing		
		* Cap. / I.R. Measurement to be made after de-aging at 150° C	at 150+0 / -10℃ and 48±4 hours storage. Meet Table6.		
		for 1hr then set for 48±4 hrs at room temp			
			Table6		
			Appearance	No damaged	
			Cap. Change	Within±12.5%	
		公有 1	L.R.	50Ω·F min	
		HE HE KIN	DC Resistance	0.05Ω max	

APPENDIXES



ASC_Feed_Through_FT_026A_AS

Example of customer label



*Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

			ALE ALE	
No.	Name		X7R- (-)	
1	Ceramic material		BaTiO ₃ based	3
2	Inner electrode		HILL SK NI	
3		Inner layer	Pusa P	
4	Termination	Middle layer	A PASSIVENEYSTEM ALLIANCE	Φ
5		Outer layer	Sn Sn	Fig. 5 The construction of MLCC
			in the chology Corport Hills	

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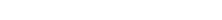
Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

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Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

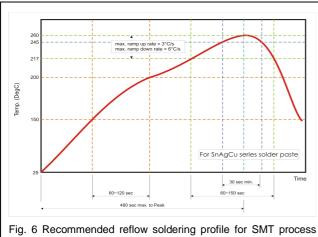


Fig. 6 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.

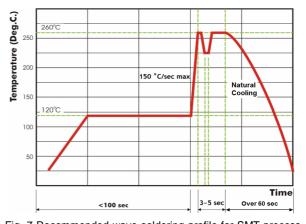


Fig. 7 Recommended wave soldering profile for SMT process with SnAgCu series solder.

